



Product Change Notification: ALAN-08WUSV762

Date:

13-Jul-2026

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7566 Final Notice: Qualification of ANAP as an additional assembly site for selected ATSAM3S4AA-AUR, ATSAM3S2AA-AUR, ATSAM3S1AB-AUR, ATSAM3S2AA-AU, ATSAM3S4AA-AU, and ATSAM3S1AB-AU catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

Affected CPNs:

[ALAN-08WUSV762_Affected_CPN_07132026.pdf](#)

[ALAN-08WUSV762_Affected_CPN_07132026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ANAP as an additional assembly site for selected ATSAM3S4AA-AUR, ATSAM3S2AA-AUR, ATSAM3S1AB-AUR, ATSAM3S2AA-AU, ATSAM3S4AA-AU, and ATSAM3S1AB-AU catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	ATX Semiconductor (Shanghai) Co.	ATX Semiconductor (Shanghai) Co.	Amkor Technology Philippine	Yes

	LTD (ASSH)	LTD (ASSH)	(P1/P2), INC. (ANAP)	
Wire Material	Au	Au	Au	No
Die Attach Material	2288A (PFAS)	2288A (PFAS)	3230 (PFAS-Free)	Yes
Molding Compound Material	CEL-9200THF	CEL-9200THF	G631HQ	Yes
Lead-Frame Material	C7025	C7025	C194	Yes
Lead-Lock	No	No	Yes	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on time delivery performance by qualifying ANAP as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 13 August 2026 (date code: 2633)

Note Below EFSD: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	July 2026					August 2026				
Work Week	18	19	20	21	22		27	28	29	30	31	32	33	34	35	36
Initial PCN Issue Date			X													
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date													X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 16, 2025: Issued initial notification.

July 13, 2026: Issued final notification. Attached the Qualification Report and PFAS Elimination and Die Attach_Explanation file. Added a 'Change (Yes/No)' column and specified die attach material if PFAS affected or PFAS-free in the Pre and Post Change Summary table. Provided estimated first ship date to be on August 13, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf

PCN_ALAN-08WUSV762 Pre and Post Change Summary.pdf

PCN_ALAN-08WUSV762 Qual Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

ATSAM3S4AA-AUR

ATSAM3S2AA-AUR

ATSAM3S1AB-AUR

ATSAM3S2AA-AU

ATSAM3S4AA-AU

ATSAM3S1AB-AU

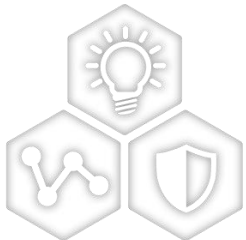
CCB 7566

Pre and Post Change Summary

PCN# ALAN-08WUSV762



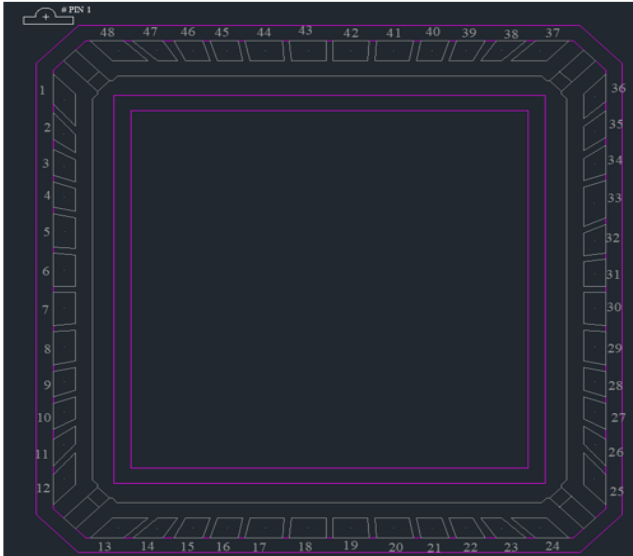
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

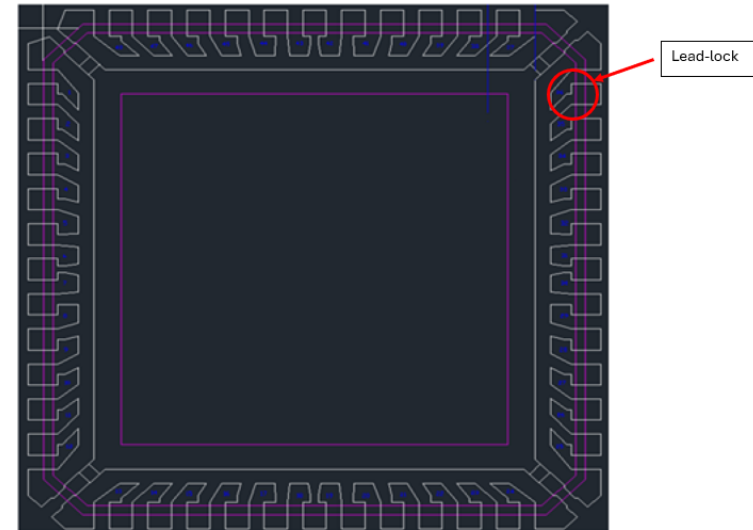
Pre and Post Change Summary

ASSH



Lead-frame Material	C7025
Lead Lock	No

ANAP



Lead-frame Material	C194
Lead Lock	Yes (L-type locking lug)

Note: Not fit to scale



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: ALAN-08WUSV762

Date: June 29, 2026

Qualification of ANAP as an additional assembly site for selected ATSAM3S4AA-AUR, ATSAM3S2AA-AUR, ATSAM3S1AB-AUR, ATSAM3S2AA-AU, ATSAM3S4AA-AU, and ATSAM3S1AB-AU catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of ANAP as an additional assembly site for selected ATSAM3S4AA-AUR, ATSAM3S2AA-AUR, ATSAM3S1AB-AUR, ATSAM3S2AA-AU, ATSAM3S4AA-AU, and ATSAM3S1AB-AU catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

QUAL ID:	REQ2501595 Rev. A
MP CODE:	58Z257R8XC02
Part No.:	ATSAM3S2AA-AU
Bonding No.:	BD-003223/01
CCB No.:	7566

Lead Frame

Paddle Size:	224x224mils
Material:	C194 ESH
DAP Surface Prep:	Double Ring
Process:	Etched
Lead Lock:	Yes, Locking Lug
Part Number:	101427919
Plating Composition:	Matte Sn

Bond Wire

Wire:	Au wire
--------------	---------

Die Attach Material

Epoxy:	3230
---------------	------

Mold Compound

Mold Compound:	G631HQ
-----------------------	--------

Package

Type:	48L LQFP
Package Size:	7x7x1.4mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
ANAP262100015.000
ANAP262100016.000
ANAP262100017.000

Result: **Pass**

Conclusion:

Qualification of 58Z25 UMC 0.15um in 48L LQFP 7X7X1.4mm at ANAP is qualified for Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature as per IPC/JEDEC J-STD-020E standard and is Passed in qualification requirements.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Moisture Soak Precondition Prior to Stresses	MSL 3: 150C 24-hour Bake, 192-hour moisture soak at 65°C / 85%RH. 3x Reflow at 260°C max. Electrical test at 25°C	JESD22-A113; IPC/JEDEC J-STD-020	231 each lot / 3 lots	L1: 0/231, L2: 0/231, L3: 0/231 (Electrical); L1: 0/45, L2: 0/45, L3: 0/45	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
High Temp Storage	175°C / 504 hours Electrical test at 25°C	JESD22-A103	45 each lot / 1 Lot	L1: 0/50	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Temperature Cycling	-65°C / 150°C Air to Air / 500 Cycles Electrical test at 25°C	JESD22-A104	77 each lot / 3 lots	L1: 0/77, L2: 0/77, L3: 0/77 (Electrical); L1: 0/22, L2: 0/22, L3: 0/22; L1: 0/5, n/a, n/a (WBP/ WBS)	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Biased HAST	+130°C/85% RH / 96 hours (bias) Electrical test at +25°C	JESD22-A110	77 each lot / 3 lots	L1: 0/77, L2: 0/77, L3: 0/77	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Unbiased HAST	+130°C/85% RH / 96 hours (no bias) Electrical test at +25°C	JESD22-A118	77 each lot / 3 lots	L1: 0/77, L2: 0/77, L3: 0/77	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8-hr steam age. Dip at 245C. 100% leads >95% lead coverage.	J-STD-002 / JESD22B-102	22 / 1 lot	0/22	Pass

Eliminating PFAS from Microchip ICs



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

Microchip
August 2025

Eliminating PFAS from MCHP ICs

- **What is PFAS**
- **Microchip's Environmental Stewardship**
- **Microchip Products with PFAS**
- **Time Frame to PFAS-Free Die Attach**
- **What is Die Attach**
- **Will clients be required to switch to PFAS free products**
- **Risk Assessment**

What is PFAS: Poly(Per) FluoroAlkyL Substances (**PFAS**)

Poly(Per) FluoroAlkyL Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
 - PFAS can be in the product itself.
 - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving “PFAS-Free” status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

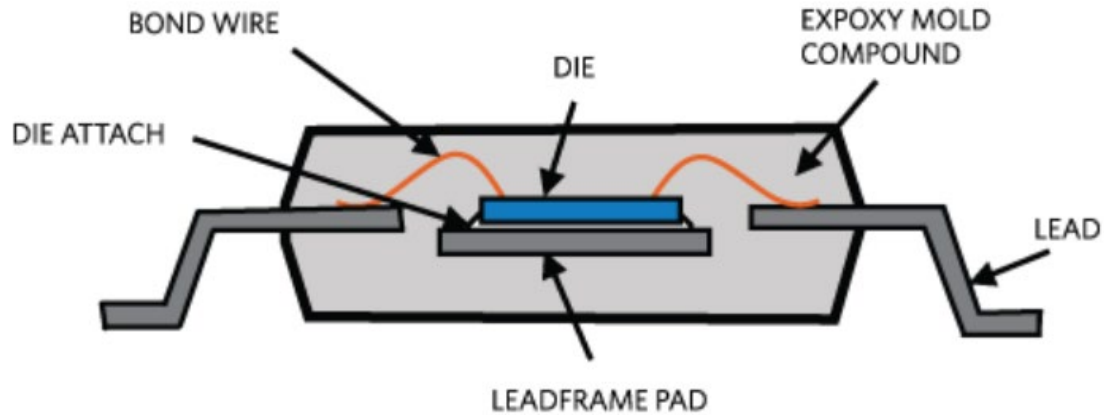
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.

